## BUK454-800A/B

### **GENERAL DESCRIPTION**

N-channel enhancement mode field-effect power transistor in a plastic envelope.

The device is intended for use in Switched Mode Power Supplies (SMPS), motor control, welding, DC/DC and AC/DC converters, and in general purpose switching applications.

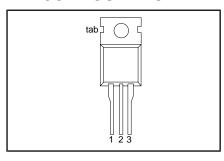
### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
V <sub>DS</sub> I <sub>D</sub> P <sub>tot</sub> R <sub>DS(ON)</sub>	BUK454 Drain-source voltage Drain current (DC) Total power dissipation Drain-source on-state resistance	<b>-800A</b> 800 2.4 85 6	-800B 800 2.0 85 8	V A W Ω

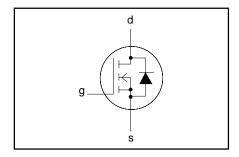
## **PINNING - TO220AB**

PIN	DESCRIPTION	
1	gate	
2	drain	
3	source	
tab	drain	

## **PIN CONFIGURATION**



## **SYMBOL**



### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MA	۸X.	UNIT
V <sub>DS</sub> V <sub>DGR</sub> ±V <sub>GS</sub>	Drain-source voltage Drain-gate voltage Gate-source voltage	$R_{GS} = 20 \text{ k}\Omega$	- - -	80	00 00 0	V V V
I <sub>D</sub> I <sub>D</sub> I <sub>DM</sub>	Drain current (DC) Drain current (DC) Drain current (pulse peak value)	T <sub>mb</sub> = 25 °C T <sub>mb</sub> = 100 °C T <sub>mb</sub> = 25 °C	- - -	<b>-800A</b> 2.4 1.5 9.5	<b>-800B</b> 2.0 1.25 8	A A A
$\begin{array}{c} P_{tot} \\ T_{stg} \\ T_{j} \end{array}$	Total power dissipation Storage temperature Junction Temperature	T <sub>mb</sub> = 25 °C -	- - 55 -	1 :	.5 50 50	Č Č

## THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-mb</sub>	Thermal resistance junction to mounting base		-	1	1.47	K/W
R <sub>th j-a</sub>	Thermal resistance junction to ambient		-	60	-	K/W

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### STATIC CHARACTERISTICS

 $T_{mb}$  = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_{D} = 0.25 \text{ mA}$	800	-	-	V
V <sub>GS(TO)</sub> I <sub>DSS</sub> I <sub>DSS</sub> I <sub>GSS</sub> R <sub>DS(ON)</sub>	Gate threshold voltage Zero gate voltage drain current Zero gate voltage drain current Gate source leakage current Drain-source on-state	$ \begin{array}{l} V_{DS} = V_{GS}; \ I_D = 1 \ \text{mA} \\ V_{DS} = 800 \ \text{V}; \ V_{GS} = 0 \ \text{V}; \ T_j = 25 \ \text{°C} \\ V_{DS} = 800 \ \text{V}; \ V_{GS} = 0 \ \text{V}; \ T_j = 125 \ \text{°C} \\ V_{GS} = \pm 30 \ \text{V}; \ V_{DS} = 0 \ \text{V} \\ V_{GS} = 10 \ \text{V}; \end{array} $	2.1 - - -	3.0 2 0.1 10 5	4.0 20 1.0 100 6	V μΑ mA nA
US(ON)	resistance	I <sub>D</sub> = 1.0 A BUK454-800B	-	6	8	Ω

## **DYNAMIC CHARACTERISTICS**

 $T_{mb}$  = 25 °C unless otherwise specified

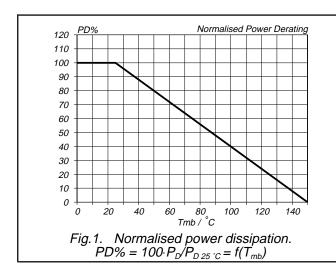
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
g <sub>fs</sub>	Forward transconductance	V <sub>DS</sub> = 25 V; I <sub>D</sub> = 1.0 A	1.0	2.3	-	S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input capacitance Output capacitance Feedback capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	- - -	450 42 15	750 70 30	pF pF pF
t <sub>d on</sub> t <sub>r</sub> t <sub>d off</sub> t <sub>f</sub>	Turn-on delay time Turn-on rise time Turn-off delay time Turn-off fall time	$\begin{array}{l} V_{\text{DD}} = 30 \text{ V; } I_{\text{D}} = 1.9 \text{ A;} \\ V_{\text{GS}} = 10 \text{ V; } R_{\text{GS}} = 50 \Omega; \\ R_{\text{gen}} = 50 \Omega \end{array}$	- - - -	15 25 50 30	20 40 65 40	ns ns ns ns
L <sub>d</sub>	Internal drain inductance Internal drain inductance	Measured from contact screw on tab to centre of die Measured from drain lead 6 mm	-	3.5 4.5	-	nH nH
L <sub>s</sub>	Internal source inductance	from package to centre of die Measured from source lead 6 mm from package to source bond pad	-	7.5	-	nH

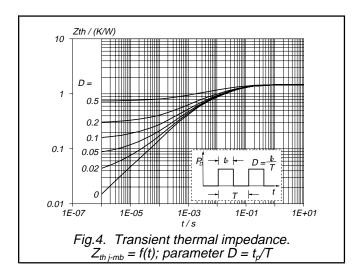
# **REVERSE DIODE LIMITING VALUES AND CHARACTERISTICS**

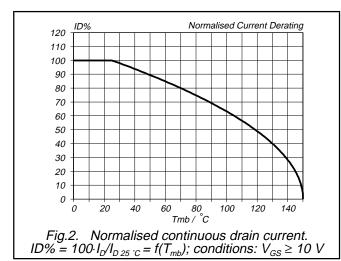
 $T_{mb}$  = 25 °C unless otherwise specified

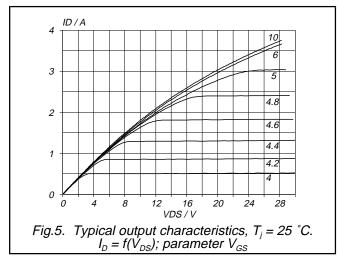
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{DR}$	Continuous reverse drain current	-	1	-	2.6	Α
${\sf I}_{\sf DRM} \ {\sf V}_{\sf SD}$	Pulsed reverse drain current Diode forward voltage	$I_F = 2.6 \text{ A}$ ; $V_{GS} = 0 \text{ V}$	-	- 1.0	10 1.3	A V
t <sub>rr</sub> Q <sub>rr</sub>	Reverse recovery time Reverse recovery charge	$I_F = 2.6 \text{ A}; -dI_F/dt = 100 \text{ A/}\mu\text{s}; \ V_{GS} = 0 \text{ V}; \ V_R = 100 \text{ V}$	1 1	230 1.9	1 1	ns μC

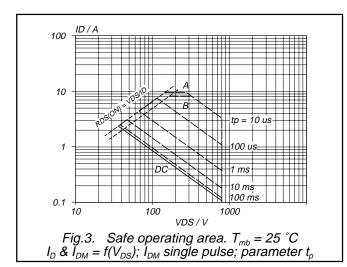
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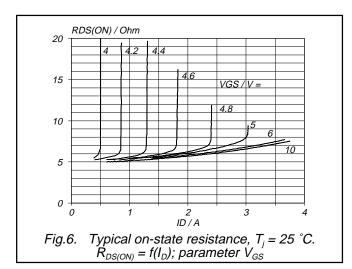




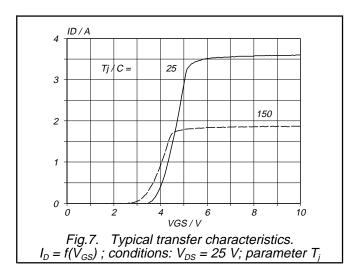


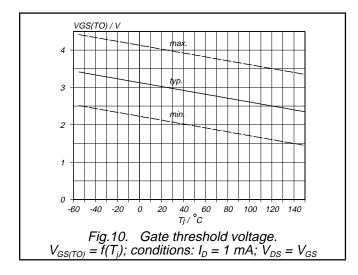


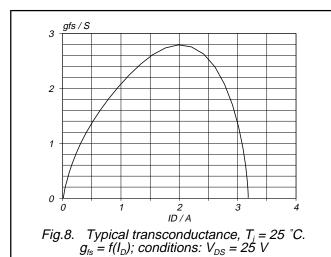


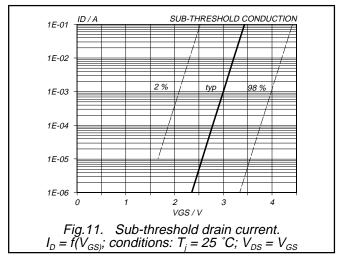


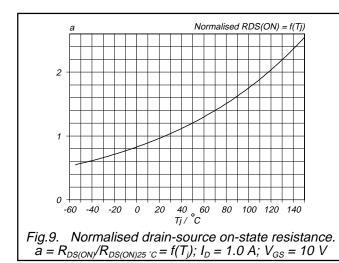
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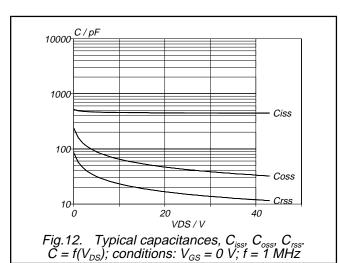












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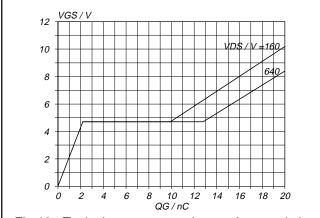
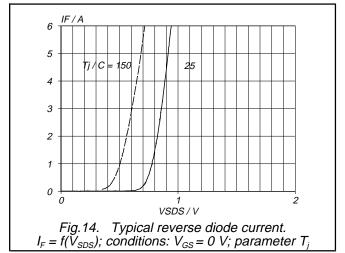
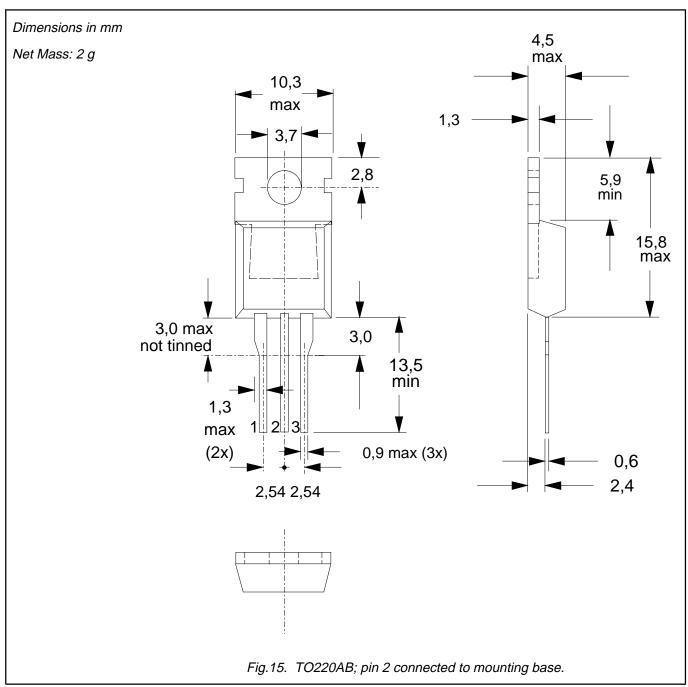


Fig.13. Typical turn-on gate-charge characteristics.  $V_{GS} = f(Q_G)$ ; conditions:  $I_D = 2.4$  A; parameter  $V_{DS}$ 



### **MECHANICAL DATA**



- Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
   Refer to mounting instructions for TO220 envelopes.
   Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product Specification

#### PowerMOS transistor

BUK454-800A/B

#### **DEFINITIONS**

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				

#### Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

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